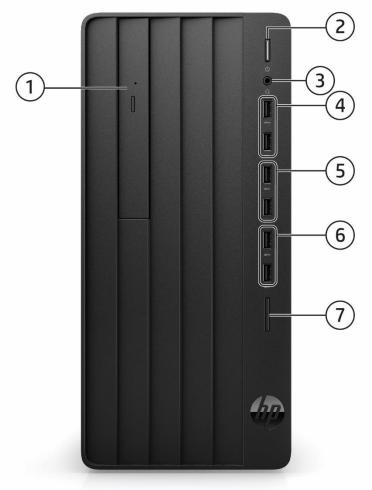
HP Pro Tower 288 G9 PCI Desktop PC

QuickSpecs

Overview

HP Pro Tower 288 G9 PCI Desktop PC



- 1. Slim-height Bay supporting an optical disk drive (Optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. (2) SuperSpeed USB 5Gbps signaling rate port¹
- 5. (2) SuperSpeed USB 10Gbps signaling rate port¹
- 6. (2) SuperSpeed USB 5Gbps signaling rate port¹
- 7. SD Card Reader (Optional)

<u>Not shown</u>

Slots

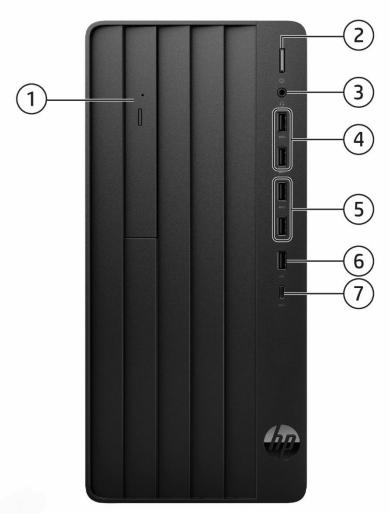
(1) PCI Express 4.0 x16²
 (1) PCI Express 3.0 x1
 (1) PCI³
 (1) M.2 for WLAN
 (1) M.2 2242/2280 storage

Bays

- (2) 3.5"(1) 9.5mm internal optical drive bay
- 1. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1.
- 2. Support discrete graphic cards and storage devices only.
- 3. Available on select skus only.



Overview



HP Pro Tower 288 G9 PCI Desktop PC (Intel 13th Gen)

- 1. Slim-height Bay supporting an optical disk drive (Optional)
- 2. Power Button
- 3. Combo jack, Headphone/ Microphone
- 4. (2) SuperSpeed USB 5Gbps signaling rate port¹
- 5. (2) SuperSpeed USB 10Gbps signaling rate port¹
- 6. (1) USB 2.0 port ¹
- 7. (1) USB-C 3.2 G1 (5G)

<u>Not shown</u>

Slots

(1) PCI Express 4.0 x16
 (1) PCI Express 3.0 x1
 (1) PCI
 (1) M.2 for WLAN
 (1) M.2 2242/2280 storage

Bays (2) 3.5"

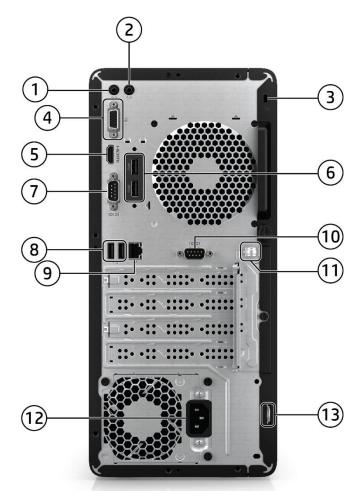
(1) 9.5mm internal optical drive bay

1. SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1.



Overview

HP Pro Tower 288 G9 PCI Desktop PC



- 1. Audio Line out
- 2. Audio Line in
- 3. Standard lock slot
- 4. VGA Port¹
- 5. HDM Port¹
- 6. Connector (2) USB 2.0 port (Optional)²

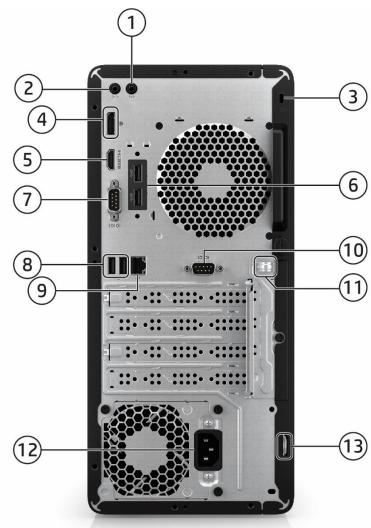
<u>Not shown</u>

- (1) PS/2 Port (Optional)
- (1) Parallel Port (Optional via PCIex1 slot)
- (1) 4 Serial Port (Optional via PCIex1 slot)⁴
- (1) Internal Speaker (Optional)
- (1) Intrusion Sensor (Optional)
- 1. Port will be covered up when configured with processor which is without internal graphics.
- 2. Available on select skus only.
- 3. Power cord connector will be in different position, depends on which power supply configured.
- 4. Available in select countries only.

- 7. Serial Port²
- 8. Connector (2) USB 2.0 port
- 9. RJ-45 Network
- 10. Serial Port (Optional)
- 11. Integrated accessories cable lock
- 12. Power Cord Connector³
- 13. Padlock Loop



Overview



HP Pro Tower 288 G9 PCI Desktop PC (Intel 13th Gen)

- 1. Audio Line out
- 2. Audio Line in
- 3. Standard lock slot
- 4. DisplayPort¹
- 5. HDM port¹
- 6. Connector (2) USB 2.0 port (optional)²

<u>Not shown</u>

Slots

- (1) PS/2 Port (Optional)
- (1) Parallel Port (Optional via PCIex1 slot)
- (1) 4 Serial Port (Optional via PCIex1 slot)³
- (1) Internal Speaker (Optional)
- (1) Intrusion Sensor (Optional)

- 7. Serial port²
- 8. Connector (2) USB 2.0 port
- 9. RJ-45 Network
- 10. Serial port (optional)
- 11. Integrated accessories cable lock
- 12. Power cord connector
- 13. Padlock loop

Bays

(2) 3.5"(1) 9.5mm internal optical drive bay

1. Port will be covered up when configured with processor which is without internal graphics.

- 2. Power cord connector will be in different position, depends on which power supply configured.
- 3. Available in select countries only.



Overview

AT A GLANCE

- Windows 11 Pro 64, Win 11 Home 64, Win 11 Pro 64 Downgrade (Win 10 Pro 64) or FreeDOS.
- Intel[®] H670 or H770¹ chipset supporting Intel[®] 12th or 13th processors¹ featuring Intel[®] UHD Graphics.
- Supports an optional discrete graphics card.
- Integrated 10/100/1000 Ethernet Controller or ac 2x2 +Bluetooth 5 M.2 2230 PCI-e+USB WW or 802.11ac (1x1) Wi-Fi[®] and Bluetooth[®] 4.2 Combo or Realtek 8852BE Wi-Fi 6 +Bluetooth[®] 5.2 Screw WLAN
- Up to 64GB DDR4- 3200 Unbuffered Memory (UDIMM).
- Independent monitor support via VGA and HDMI interfaces.
- TPM2.0 support (PCI version support dTPM, and the non-PCI version support fTPM)¹.
- Supports both Hard Disk Drives and PCIe[®] NVMe[™] M.2 SSD or PCIe[®] NVMe[™] TLC M.2 SSD.
- Up to 10 USB Ports (including native 4 SuperSpeed USB 5Gbps signaling rate ports and 2 SuperSpeed USB 10Gbps signaling rate ports and 2 USB 2.0 ports).
- 180W/350W/500W 90% HE power supply and 260W 92% HE power supply.
- Security cable lock supported (sold separately).
- Intrusion sensor supported (Optional).
- Optional HP Services available²; terms and conditions vary by country; certain restrictions and exclusions apply.

1. Available on select skus only.

2. HP Services are optional. Service levels and response times for HP Care Services may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

PRODUCT NAME

HP Pro Tower 288 G9 PCI/G9 E PCI Desktop PC

OPERATING SYSTEM

Preinstalled	Windows 11 Pro ¹
	Windows 11 Home - HP recommends Windows 11 Pro for Business ¹
	Windows 11 Home Single Language - HP recommends Windows 11 Pro for Business ¹
	Windows 11 Pro (preinstalled with Windows 10 Pro Downgrade) ^{1,2}
	FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.



Standard Features and Configurable Modules

PROCESSORS

Intel® Celeron® Processors^{1,2} CPU Intel Celeron G6900 Dual Core 3.4GHz 3200MHz 46W (3.4GHz, 4MB cache, 2 cores)

Intel[®] Pentium[®] Processors^{1,2}

CPU Intel Pentium Gold G7400 Dual Core 3.7GHz 3200MHz 46W (3.7GHz, 6MB cache, 2 cores)

Intel 12th Processors

Intel® Core™ i3¹

CPU Intel Core i3-12100 4C 3.3GHz 3200MHz 60W (3.3GHz, turbo up to 4.3GHz, 12MB cache, 4 cores)

Intel® Core™ i5¹

CPU Intel Core i5-12400 6C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.4GHz, 18MB cache, 6 cores) CPU Intel Core i5-12500 6C 3.0GHz 3200MHz 65W (3.0GHz, turbo up to 4.6GHz, 18MB cache, 6 cores)

Intel® Core™ i7¹

CPU Intel Core i7-12700 12C 2.1GHz 3200MHz 65W (2.1GHz, Up to 4.8GHz with Intel® Turbo Boost², 25MB cache, 12 cores)

Intel 13th Processors

Intel® Core™ i3¹

CPU Intel Core i3-13100 4C 3.4GHz 3200MHz 60W (3.4GHz, turbo up to 4.5GHz, 12MB cache, 4 cores)

Intel® Core™ i5¹

CPU Intel Core i5-13400 10C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.6GHz, 20MB cache, 10 cores) CPU Intel Core i5-13500 14C 2.5GHz 3200MHz 65W (2.5GHz, turbo up to 4.8GHz, 24MB cache, 14 cores)

Intel® Core™ i7¹

CPU Intel Core i7-13700 16C 2.1GHz 3200MHz 65W (2.1GHz, Up to 5.2GHz with Intel® Turbo Boost², 30MB cache, 16 cores)

 Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. 64-bit computing system required. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
 Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information.



Standard Features and Configurable Modules

CHIPSET

Intel® H670/H770 Chipset

GRAPHICS

Integrated^{1,2}

Intel[®] UHD Graphics 770 Graphics 730 Graphics 710

Discrete Graphics

AMD Radeon™ RX 6600XT Graphics (8 GB GDDR6) AMD Radeon™ RX 6400 Graphics (4 GB GDDR6) AMD Radeon™ RX 6300 Graphics (2 GB GDDR6) NVIDIA® Quadro® T400 (4 GB GDDR6 dedicated) NVIDIA® GeForce RTX 3050 Graphics (8 GB GDDR6) NVIDIA® GeForce RTX 4060 Graphics (8 GB GDDR6)

1. HD content required to view HD images.

2. Integrated Intel software is available on select models only and requires separately purchased projector, tv or computer monitor with an integrated or external receiver. External receivers connect to the projector, tv or computer monitor via a standard VGA, HDMI cable, also sold separately.

***NOTE:** Available in select countries only.

MEMORY

Form Factor	Туре	Maximum	# of Slots
Tower	DDR4 3200	64 GB capacity	2 DIMM ¹
4GB DDR4-3200 UDIM	M NECC (1x4GB)		
8GB DDR4-3200 UDIM	M NECC (1x8GB)		
8GB DDR4-3200 UDIM	M NECC (2x4GB) ²		
16GB DDR4-3200 UDI	MM NECC (1x16GB)		
16GB DDR4-3200 UDI	MM NECC (2x8GB) ²		
32GB DDR4-3200 UDI	MM NECC (1x32GB)		
32GB DDR4-3200 UDI	MM NECC (2x16GB) ²		
64GB DDR4-3200 UDI	MM NECC (2x32GB) ²		

1. Memory modules support data transfer rates up to 2933 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

2. Memory speed 3200 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number. **NOTE:** DDR4-2933 UDIMM is only available for 10th Gen i7 processor.



Standard Features and Configurable Modules

STORAGE

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

SATA3 - 3.5" or 2.5" 6Gb/s HDDs

2TB 7200 RPM SATA Hard Disk Drive 1TB 7200 RPM SATA Hard Disk Drive 500GB 7200 RPM SATA Hard Disk Drive

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software.

Solid State Drives

256GB* M.2 NVMe 512GB* M.2 NVMe 1TB* M.2 NVMe 128GB* M.2 2230 PCIe NVMe* 128GB* M.2 2280 PCIe NVMe Three Layer Cell SSD 256GB* M.2 2280 PCIe NVMe Three Layer Cell SSD 512GB* M.2 2280 PCIe NVMe Three Layer Cell SSD 1TB* M.2 2280 PCIe NVMe Three Layer Cell SSD

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) of system disk is reserved for the system recovery software. ***NOTE:** Available in select countries only.

SD Card Reader¹

SD/SDHC/SDXC SD Card Reader

1. Optional per configuration and available in select countries only.

OPTICAL DISC DRIVES

DVD-ROM 9.5mm DVD-Writer¹ 9.5mm

1. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing singlelayer DVD drives and players.



Standard Features and Configurable Modules

NETWORKING¹

Ethernet (RJ-45)

Integrated 10/100/1000M GbE LAN

Wi-Fi[®] and Bluetooth[®]

Realtek RTL8852BE Wi-Fi6+ Bluetooth[®] 5.2 Realtek RTL8822CE-CG 802.11a/b/g/n/ac (2x2) with Bluetooth[®] M.2 PCIe[®] Realtek RTL8821CE-CG 802.11a/b/g/n/ac (1x1) with Bluetooth[®] M.2 PCIe[®]

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

NOTE: Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited.

AUDIO / MULTIMEDIA

Realtek ALC3867-CG Integrated Hi-Definition Audio Combo Jack, Headphone / Microphone Line-in / Line-out (3.5mm)

KEYBOARDS AND POINTING DEVICES¹

Keyboard

HP USB 320K Keyboard HP 125 BLK Wired Keyboard HP 125 Antimicrobial Wired Keyboard (china only) HP PS/2 Business Slim Keyboard (for machine configured with PS/2 port)

Mouse

HP PS/2 mouse (for machine configured with PS/2 port) HP Wired Desktop 320M mouse HP 125 Wired Mouse HP 128 Laser Wired Mouse HP 125 Antimicrobial Wired Mouse (china only)

1. Keyboards and mouse are optional or add-on features. A keyboard and mouse are required for this device. If you do not already have a keyboard and mouse, please refer to a list of compatible keyboards on the "Recommended Accessories" page.

PORTS

Front

Slim-height Bay - supporting an optical disk drive (Optional)
Power Button
Combo jack, Headphone / Microphone
SD Card Reader (Optional)
(2) SuperSpeed USB 10Gbps signaling rate port*
(4) SuperSpeed USB 5Gbps port* or (2) SuperSpeed USB 5Gbps signaling rate port
(1) USB 2.0*



Standard Features and Configurable Modules

(1) USB-C©*

Not shown

(1) PCI Express 4.0 x16
(1) PCI Express 3.0 x1
(1) Full-height PCI (Available on selected sku)
(1) M.2 for WLAN
(1) M.2 2230/2280 storage

Rear

Audio Line out Audio Line in HDMI Port VGA Port or Displayport* Serial Port (Optional on selected sku) 2nd Serial Port (Optional) Standard Lock Slot (4) USB 2.0 port (Optional on selected sku) (2) USB 2.0 port (Optional on selected sku) RJ-45 Network connector Power cord connector Padlock loop Integrated accessories cable lock

Not shown

- (1) PS/2 Port (Optional on selected sku)(1) Parallel Port (Optional via PCIex1 slot)
- (1) 4x Serial port (Optional via PCIex1 slot)*
- (1) Internal Speaker (Optional)
- (1) Intrusion Sensor (Optional)

NOTE*: Available in select countries only. **NOTE*:** SuperSpeed USB 10Gbps = USB 3.2 Gen2. SuperSpeed USB 5Gbps = USB 3.2 Gen1

BAYS

- (1) 9.5mm external slimline ODD bay (Optional)
- (1) 3.5" internal HDD or bay
- (1) 3.5" internal HDD bay (share bay with caddy)



Standard Features and Configurable Modules

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Security and Protection

McAfee* LiveSafe™¹

Productivity

Microsoft 365² Xerox[®] DocuShare[®] (90 days free trial offer)³

ODD Playback

sMedio True DVD for HP

Movies

Netflix⁴

App Stores and Content Purchasing

Amazon⁴

HP Utilities and Support

HP Documentation HP Audio Switch⁵ HP Support Assistant myHP

BTB

HP Setup Integrated OOBE

Hardware Enabling Drivers or software utility

HP System Event Utility

1. Free 1-year subscription of McAfee LiveSafe service included. Internet access required and not included. Subscription required after expiration 2. Sold separately and requires Internet access for activation.

3. Simply sign up and start using Xerox[®] DocuShare[®] Go. No credit card. No obligation. Data will become unavailable unless a subscription is entered before the end of the 90 day free trial period. See visit https://http://www.xerox.com/docusharego for details. 4. Internet access required and not included.

Easily switch between speaker and microphone sources with intuitive controls and a consistent app experience.
 ***NOTE**: Available in Latin America countries only.

POWER SUPPLY¹

180 W EPA90 (Gold) +12V 260W EPA92 +12V 350 W EPA90 (Gold) Power Supply 500 W EPA90 (Gold) Full range 115V/230V

1. All power supplies are not available in every region.



Standard Features and Configurable Modules

DIMENSIONS AND WEIGHT

Dimensions

6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm)

Weight

10.4 lbs / 4.7 kg

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 5° to 35° C¹ Non-operating: -30° to 60° C¹
Relative Humidity	Operating: 5% to 90% (non-condensing at ambient) Non-operating: 5% to 90% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000 m Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

Eco-Label Certifications	This product has received or is in t	This product has received or is in the process of being certified to the following approvals and may be		
& declarations	labeled with one or more of these marks:			
	• IT ECO declaration			
	• US ENERGY STAR [®]			
	 US Federal Energy Management 	5		
	• EPEAT Gold* or EPEAT Silver** registered in the United States. See http://www.epeat.net for			
	registration status in your country.			
	China Energy Conservation Program (CECP)			
	China State Environmental Protection Administration (SEPA)			
	Taiwan Green Mark			
	 Commission Regulation (EC) No 617/2013 (ErP Lot 3) 			
	Note*: Only available on 13th Gen CPU Legacy SKU, except Japan.			
	Note**: Available on all 12th Gen CPU	SKUs, 13th Gen non-legacy SKUs, and 1	3th Gen legacy SKUs for Japan.	
System Configuration		ergy Consumption and Declared Noi	se Emissions data for the	
	Desktop model is based on a "Typ	ically Configured Desktop".		
Energy Consumption				
(in accordance with US ENERGY STAR® test	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
method)				



Standard Features and Configurable Modules

Normal Operation (Short idle)	35.98 W	36.76	5 W	36 W
Normal Operation (Long idle)	33.27 W	33.03	W	32.68 W
Sleep	1.08 W	1.1	N	1.07 W
Off	0.27 W	0.3	N	0.26 W
	NOTE: Energy efficiency data listed is f family. HP computers marked with the Environmental Protection Agency (EP/ offer ENERGY STAR® compliant config featuring a hard disk drive, a high effic	ENERGY STAR® Logo A) ENERGY STAR® spe urations, then energy ciency power supply,	are compliant with cifications for comp efficiency data list and a Microsoft Win	n the applicable U.S. buters. If a model family does not ed is for a typically configured PC dows® operating system.
Heat Dissipation*	115VAC, 60Hz	230VAC,	50Hz	100VAC, 50Hz
Normal Operation (Short idle)	123.1 BTU/hr	125.7 B	TU/hr	123.1 BTU/hr
Normal Operation (Long idle)	113.8 BTU/hr	113 BT		111.8 BTU/hr
Sleep	3.7 BTU/hr	3.8 BT		3.7 BTU/hr
Off	0.9 BTU/hr	1 BTU	/hr	0.9 BTU/hr
Declared Noise	NOTE: Heat dissipation is calculated by hour.	ased on the measure	d watts, assuming t	he service level is attained for one
Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (Lwad, bels)			Gound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	3.5		23.2	
Fixed Disk – Random writes	3.6		24.8	
Optical Drive – Sequential reads	4.6		38.6	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "3" years after the end of production.			
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <silver> level, see http://www.epeat.net.</silver> Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains 28.2% post-consumer recycled plastic (by wt.) This product is 91.7% recycle-able when properly disposed of at end of life. 			

Standard Features and Configurable Modules

Packaging Materials	External:	PAPER/Paperboard	1220 g
	Internal:	PAPER/Molded Pulp	580 g
		PLASTIC/Polyethylene low density - LDPE	40 g
		packaging material contains at least 0.0% recycled conten	
	The corrugated paper packaging materials contains at least 35.0% recycled content.		
Material Usage			is of regulatory limits (refer to If): ardants in plastics
			ail packaging has been
Packaging Usage			product packaging:
	materials. • Eliminate t • Design pac • Maximize t • Use readily • Reduce size • Plastic pac	he use of heavy metals such as lead, chromium, mercury a he use of ozone-depleting substances (ODS) in packaging kaging materials for ease of disassembly. he use of post-consumer recycled content materials in pac recyclable packaging materials such as paper and corruga e and weight of packages to improve transportation fuel e kaging materials are marked according to ISO 11469 and D	materials. ckaging materials. ated materials. fficiency. DIN 6120 standards.
End-of-life		s end-of-life HP product return and recycling programs in	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,
Management and Recycling		product, please go to: http://www.hp.com/go/reuse-recyc Products returned to HP will be recycled, recovered or disp	
	each product is posted on may be used integrate an Global Citize http://www. Eco-label cer	E directive (2002/95/EC) requires manufacturers to provide t type for use by treatment facilities. This information (pro the Hewlett Packard web site at: http://www.hp.com/go/r by recyclers and other WEEE treatment facilities as well a d re-sell HP equipment. nship Report hp.com/hpinfo/globalcitizenship/gcreport/index.html rtifications 3.hp.com/us/en/hp-information/environment/ecolabels.html	duct disassembly instructions) ecyclers. These instructions s HP OEM customers who



Standard Features and Configurable Modules

ISO 14001 certificates:
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_
Certificate.pdf
and
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

On-site Warranty¹: Available three-year (3-3-3) or one-year (1-1-1) limited warranty (varies by country) delivers on-site, next business day² service for parts and labor and complimentary limited technical support³. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack⁴ To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.

1: Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region. 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country. 3: Technical support applies only to HP-configured and third-party HP qualified hardware and software.

4: Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications - Graphics

GRAPHICS

Intel® UHD Graphics (integrate	ed)
Graphics Controller	Integrated
DisplayPort™	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 4 displays connected to any output controlled by Intel® Graphics
HDMI	Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI
VGA	VGA output
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12
Supported Display Resolutions and Refresh Rates	Max. Resolution (VGA) 2048 x 1536 @60Hz Max. Resolution (HDMI) 7680 x 4320 @60Hz

Note: The actual amount of maximum graphics memory can be less than the amounts listed above depending upon your computer's configuration.

Note: other resolutions may be available but are not recommended as they may not have been tested and qualified by HP Only supported on displays connected to the external DisplayPort[™] connector.

AMD Radeon™ RX 6300 4GB Graphics Card

Engine Clock	1512MHz (Game) 2040MHz (Boost)
Memory Clock	2000 MHz
Memory Size(width)	2GB (64-bit)
Memory Type	512M x 32 GDDR6
Max. Resolution (HDMI)	7680 x 4320x 36bpp@60Hz
Max. Resolution (DP)	7680 x 4320 x 24bpp@120Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	HDMI+DP
Cooling (active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption (W)	32W
PCB form-factor with bracket	LP PCB with FH/LP bracket



Technical Specifications - Graphics

AMD Radeon™ RX 6400 4GB Graphics Card

Engine Clock	1923MHz
Memory Clock	2000MHz
Memory Size(width)	4GB (64-bit)
Memory Type	512M x 32 GDDR6
Max. Resolution (HDMI)	7680 x 4320@60Hz
Max. Resolution (DP)	7680 x 4320@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors (bracket)	HDMI+DP
Cooling (active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption (W)	50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon™ RX6600XT 8 GB Graphics Card

Engine Clock	1280MHz
Memory Clock	1000MHz
Memory Size(width)	8GB (128-bit)
Memory Type	512M x 32 GDDR6
Max. Resolution (HDMI)	7680 x 4320@60Hz
Max. Resolution (DP)	7680 x 4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	HDMI+DPx3
Cooling (active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption (W)	162.5W
PCB form-factor with bracket	FH PCB with FH bracket

NVIDIA® Quadro T400 Graphics Card

	2100MU-
Engine Clock	2100MHz
Memory Clock	5001MHz
Memory Size (width)	4GB (64-bit)
Memory Type	256M x 16 GDDR6
Max. Resolution (DP)	7680 x 4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors (bracket)	mDPx3
Cooling (active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption (W)	30W
PCB form-factor with bracket	LP PCB with LP bracket



Technical Specifications - Graphics

NVIDIA® GeForce RTX 3050 8GB Graphics Card

Engine Clock	1515MHz
Memory Clock	7000MHz
Memory Size (width)	8GB (128-bit)
Memory Type	512M x 32 GDDR6
Max. Resolution (DP)	7680 x 4320@60Hz
Multi Display Support	7680x4320@60Hz (DSC)
HDCP Compliance	Up to 4 displays
Rear I/O connectors (bracket)	Yes
Cooling (active/passive)	DPx3+ HDMIx1
Total power consumption (W)	Active fansink with 4 pin fan control
PCB form-factor with bracket	120W

NVIDIA® GeForce RTX 4060 8GB Graphics Card

Engine Clock	1830Mhz
Memory Clock	17Gbps
Memory Size (width)	8GB (128-bit)
Memory Type	512M x 32 GDDR6
Max. Resolution (DP)	7680 x 4320@60Hz
Multi Display Support	7680 x 4320@60Hz
HDCP Compliance	Up to 4 displays
Rear I/O connectors (bracket)	Yes
Cooling (active/passive)	DPx3+ HDMIx1
Total power consumption (W)	Active fansink
PCB form-factor with bracket	115W

Technical Specifications – Optical Drives

STORAGE*

NOTE: Starting from November 1st, 2023, all shipments will require Windows to be installed when selecting a SSD. HDD can only be configured as additional data drives and not as the boot drive.

HP 2TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	2TB
Rotational Speed	7,200 rpm
Interface	SATA 6Gb/s NCQ
Buffer Size	64MB
Logical Blocks	3,907,029,168
Seek Time	Read: <8.5 ms Write: <9.5 ms
Height	1.028 in/26.11 mm
Width	4.0 in/101.6 mm
Operating Temperature	32° to 140° F (0° to 60° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	Serial ATA 3.0 (6.0 Gb/s)
Buffer Size	32MB
Logical Blocks	1,953,525,168
Seek Time	Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

500GB 7.2K rpm SATA 6.0Gb/s 3.5" Hard Disk Drive

Capacity	500GB
Rotational Speed	7,200 rpm
Interface	Serial ATA 3.0 (6.0 Gb/s)
Buffer Size	32MB
Logical Blocks	1,953,525,168
Seek Time	Single Track: 2.0 ms Average: 11 ms Full-Stroke: 21 ms



Technical Specifications – Optical Drives

Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

128GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications – Optical Drives

512GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3x4
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

256GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

512GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]



Technical Specifications – Optical Drives

Features

APST; ASPM L1.2; NVME spec 1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

500GB 7200RPM 2.5in SATA HDD

Capacity	500GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

1TB 7200RPM 2.5in SATA HDD

Capacity	1TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.

128GB M.2 2230 PCIe NVMe SSD

Drive Weight Capacity Height Length	< 10g 128GB 2.3mm 30mm
Width	22mm
Interface	PCIE NVMe
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	290,069,680
Operating Temperature Features	0° to 70°C (32° to 158°F) [ambient temp] Pyrite

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB (for Windows) is reserved for system recovery software.



Technical Specifications – Optical Drives

OPTICAL DISC DRIVES

HP 9.5mm Desktop G2 Slim DVD Writer Drive

Height	9.5 mm height		
Orientation	Either horizontal or vertical		
Interface type	SATA/ATAPI		
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB s	tandard	
Dimensions (W x H x D)	•	9.5 x 127 mm) without bezel	
Weight (max)	0.31 lb (140 q)		
-			
Read Speeds	DVD-R DL	Up to 6X	
	DVD+R	Up to 8X	
	DVD+RW	Up to 8X	
	DVD+R DL	Up to 6X	
	DVD-R	Up to 8X	
	DVD-RW	Up to 6X	
	CD-R	Up to 24X	
	CD-RW	Up to 10X	
	DVD-RW, DVD+RW	Up to 8X	
	DVD-R DL, DVD+R DL	Up to 8X	
	DVD+R, DVD-R	Up to 8X	
	DVD-ROM DL, DVD-ROM	Up to 8X	
	CD-ROM, CD-R	Up to 24X	
	CD-RW	Up to 24X	
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)		
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)		
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)		



Technical Specifications – Optical Drives

HP 9.5mm Desktop G2 Slim DVD-ROM Drive

Height	9.5 mm height		
Orientation	Either horizontal or vertical		
Interface type	SATA/ATAPI		
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB s	tandard	
Dimensions (W x H x D)	•	9.5 x 127 mm) without bezel	
Weight (max)	0.31 lb (140 g)		
Read Speeds	DVD-R DL	Up to 6V	
keau speeus	DVD-R DL DVD+R	Up to 6X	
	DVD+R DVD+RW	Up to 8X	
	DVD+R DL	Up to 8X Up to 6X	
	DVD+R DL	Up to 8X	
	DVD-RW	Up to 6X	
	CD-R	Up to 24X	
	CD-RW	Up to 10X	
	DVD-RW, DVD+RW	Up to 8X	
	DVD-R DL, DVD+R DL	Up to 8X	
	DVD-R DL, DVD-R DL	Up to 8X	
	DVD-ROM DL, DVD-ROM	Up to 8X	
	CD-ROM, CD-R	Up to 24X	
	CD-RW	Up to 24X	
a	•••	•	
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)		
Power	Source Slimline SATA DC power receptacle		
	DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)		
Environmental conditions	Temperature 41° to 122° F	(5° to 50° C)	
(operating - non-condensing)	Relative Humidity 10% to 8		
	Maximum Wet Bulb Temperature 84° F (29° C)		

Technical Specifications – Networking

NETWORKING

10/100/1000 NIC	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
		100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
		1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
		Auto-Negotiation (Automatic Speed Selection)
		Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power	ACPI compliant – multiple power modes
	Management	Situation-sensitive features reduce power consumption
		Advanced link down power saving for reducing link down power consumption
	Performance	TCP/IP/UDP Checksum Offload (configurable)
	Features	Protocol Offload (ARP & NS)
		Large send offload and Giant send offload
		Receiving Side Scaling
		Jumbo Frame 9K
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up
		Frame); Wake-on-LAN from off (Magic Packet only)
		PXE 2.1 Remote Boot
		Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause
		30)
		Comprehensive diagnostic and configuration software suite
		Virtual Cable Doctor for Ethernet cable status
	Interface	PCIe + SMBus
	NIC Device Driver Name	PCIe GBE Ethernet Family Controller

Realtek 802.11ac (1x1) Wi-Fi 5 and Bluetooth® 4.2 Combo

Wireless LAN Standards ¹	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.	
Interoperability	Wi-Fi® certified modules	
Frequency Bands	802.11b/g/n	2.402 – 2.482 GHz NOTE: The FCC has declared products that utilize passive scanning on channel
		12/13 and are capable of transmitting must fully comply with requirements of 15.247 & 15.249 or otherwise disable those channels.
	802.11a/n	4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz
		5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz



Data Rates	802.11b: 1, 2, 5.5, 11 Mbps
butu nutes	802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	δύζ. 1 Tác. MCSU ~ MCS9, (155, and 255) (20Μπ2, 40Μπ2, and δύΜπ2)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ²	IEEE and 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	802.1x authentication
	WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	IEEE 802.11i
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite
	WAPI
	2 Check latest software/driver release for updates on supported security features.
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ³	802.11b: +14dBm minimum
	802.11g: +12dBm minimum
	802.11a: +12dBm minimum
	802.11n HT20(2.4GHz): +12dBm minimum
	802.11n HT40(2.4GHz): +12dBm minimum
	802.11n HT20(5GHz): +10dBm minimum
	802.11n HT40(5GHz): +10dBm minimum
	802.11ac VHT80(5GHz): +10dBm minimum
	3. Maximum output power may vary by country according to local regulations.
Power Consumption	•Transmit mode2.0 W
	•Receive mode1.6 W
	•Idle mode (PSP)180 mW(WLAN Associated)
	•Idle mode50 mW(WLAN unassociated)
	•Connected Standby 10mW •Radio disabled8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode



Receiver Sensitivity⁴	802.11b, 1Mbps: -93.5dBm maximum	802.11b, 1Mbps: -93.5dBm maximum	
	802.11b, 11Mbps: -84dBm maximum		
	802.11a/g, 6Mbps: -86dBm maximum		
	802.11a/g, 54Mbps: -72dBm maximum		
	802.11n, MCS07: -67dBm maximum		
	802.11n, MCS15: -64dBm maximum		
	802.11ac, MCS0: -84dBm maximum		
	802.11ac, MCS9: -59dBm maximum		
	4 Receiver sensitivity is measured at a packe error rate of 10% for 802.11a/g (OFDM modu	t error rate of 8% for 802.11b (CKK modulation) and a packet llation).	
Antenna type	Two embedded dual band 2.4/5 GHz ante	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth [®] communications	
Form Factors	PCI-Express M.2 MiniCard		
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Туре 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: Non-operating:	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)	
Humidity	Operating: Non-operating:	10% to 90% (non-condensing) 5% to 95% (non-condensing)	
Altitude	Operating: Non-operating:	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radi	LED Amber – Radio OFF; LED White – Radio ON	
HP Integrated Module with Blue	tooth® 4.0/4.1/4.2 Wireless Card Technol	ogy	
Bluetooth ^a Specification	4.0/4.1/4.2 Wireless Card Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels		
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth [®] component shall operate as a Class II Bluetooth [®] device with a maximum transmit power of + 4 dBm for BR and EDR.		

Receiver Sensitivity Legacy		
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Range	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Electrical Interface	USB 2.0 compliant	
Bluetooth [®] Software Supported Link Topology	Microsoft Windows Bluetooth [®] Software	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Certifications Bluetooth ^a Profiles Supported	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	Microsoft Windows ACPI, and USB Bus Support	
Certifications Bluetooth [®] Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)	



Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + Bluetooth® 5		
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v	
Interoperability	Wi-Fi [®] certified	
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz	
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz) 	
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ¹	 IEEE and Wi-Fi[®] compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI 1 Check latest software/driver release for updates on supported security features. 	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	



Output Power ²	• 802.11b: +18.5dBm minimum
output i onci	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
	• 802.11ac VHT160(5GHz): +11.5dBm minimum
	2. Maximum output power may vary by country according to local regulations.
Power Consumption	Transmit mode:2.0 W
	Receive mode: 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	 Idle mode:50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW
	Radio disabled: 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum
	802.11b, 11Mbps: -84dBm maximum
	802.11a/g, 6Mbps: -86dBm maximum
	802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum
	802.11n, MCS15: -64dBm maximum
	802.11ac, MCS0: -84dBm maximum
	802.11ac, MCS9: -59dBm maximum
	3 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a
	packet error rate of 10% for 802.11a/g (OFDM modulation).
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN
	MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm
	2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230: 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating: 14° to 158° F (-10° to 70° C)
	Non-operating: -40° to 176° F (-40° to 80° C)
Humidity	Operating: 10% to 90% (non-condensing) Non-operating: 5% to 95% (non-condensing)
Altitude	Operating: 0 to 10,000 ft (3,048 m)
	Non-operating: 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF;
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON



Bluetooth Specification	4.0/4.1/4.2/5.0 Wireless Card Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950-1/IEC62368-1 UL, CSA, and CE Mark
Bluetooth [®] Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek RTL8852BE Wi-Fi6 + Bluetooth® 5.2		
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n/ac • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz	
Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz) 	
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i WAPI 	
Network Architecture Models	1 Check latest software/driver release for updates on supported security features. Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	



A 1 A A A			
Output Power ²	• 802.11b: +18.5dBm minimum		
	• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum		
	• 802.11n HT20(2.4GHz): +15.5dBm minimum		
	• 802.11n HT40(2.4GHz): +14.5dBm minimum		
	• 802.11n HT20(5GHz): +15.5dBm minimum		
	• 802.11n HT40(5GHz): +14.5dBm minimum		
	• 802.11ac VHT80(5GHz): +11.5dBm minimum		
	• 802.11ac VHT160(5GHz): +11.5dBm minimum		
	2. Maximum output power may vary by country according to local regulations.		
Power Consumption	Transmit mode:2.0 W		
	Receive mode: 1.6 W		
	Idle mode (PSP) 180 mW (WLAN Associated)		
	Idle mode:50 mW (WLAN unassociated)		
	Connected Standby/Modern Standby: 10mW		
	• Radio disabled: 8 mW		
Power Management	ACPI and PCI Express compliant power management		
	802.11 compliant power saving mode		
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum		
	802.11b, 11Mbps: -84dBm maximum		
	802.11a/g, 6Mbps: -86dBm maximum		
	802.11a/g, 54Mbps: -72dBm maximum		
	802.11n, MCS07: -67dBm maximum		
	802.11n, MCS15: -64dBm maximum		
	802.11ac, MCS0: -84dBm maximum		
	802.11ac, MCS9: -59dBm maximum		
	3 Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a		
	packet error rate of 10% for 802.11a/g (OFDM modulation).		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure		
Antenna type	High efficiency antenna with spatial liversity, mounted in the display enclosure		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN		
	MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface		
Dimensions	1. Type 2230: 2.3 x 22.0 x 30.0 mm		
	2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230: 2.8g		
	2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating: 14° to 158° F (–10° to 70° C) Non-operating: –40° to 176° F (–40° to 80° C)		
Humidity	Operating: 10% to 90% (non-condensing)		
	Non-operating: 5% to 95% (non-condensing)		
Altitude	Operating: 0 to 10,000 ft (3,048 m)		
	Non-operating: 0 to 50,000 ft (15,240 m)		
	LED Amber – Radio OFF;		
LED Activity	LED AIIIDEI – RAUIO OFF,		



Bluetooth Specification	4.0/4.1/4.2/5.0 Wireless Card Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.		
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW		
Bluetooth Software Supported	Microsoft Windows Bluetooth Software		
Link Topology			
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950-1/IEC62368-1 UL, CSA, and CE Mark		
Bluetooth [®] Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		

Technical Specifications - Audio

HIGH DEFINITION AUDIO

Туре	Integrated	
HD Stereo Codec	Realtek ALC3867-CG	
Audio I/O Ports	Front side Combo jack for supporting CTIA, Rear side Line-in/ Line-out/ Mic-in jacks	
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.	
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.	
HD Audio Codec	Realtek ALC3601	
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1K/ 48 K/96K / 192K Hz for DAC and 44.1K/ 48K/ 96K/ 192K Hz Hz for ADC	
Wavetable Syntheses	Yes	
Analog Audio	Yes	
# of Channels on Line-Out	Stereo	
Internal Speaker	Yes	
External Speaker Jack*	2W class D mono amplifier for the internal speaker only. External speakers must be powered externally.	

NOTE*: Optional



Technical Specifications - Power

POWER SUPPLY

Operating Voltage Range	90 – 264 VAC
Rated Voltage Range	100-240V AC
Rated Line Frequency	50/60 HZ
Operating Line Frequency	47 – 63 Hz
Rated Input Current	180 W: <2.3A 260 W: ≦ 3.1A 350 W: <4A 500 W: <6A
Rated Input Current with Energy Efficient* Power Supply	180 W active PFC 87/90/87% efficient at 20/50/100% load (115 V) 88/92/88% efficient at 20/50/100% load (230 V); 350 W active PFC 87/90/87% efficient at 20/50/100% load (115 V) 88/92/88% efficient at 20/50/100% load (230 V) 500W active PFC 87/90/87% efficient at 20/50/100% load (115 V) 88/92/88% efficient at 20/50/100% load (230 V)
DC Output	+12 V
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	180 W/350 W: 70*25mm (linear type) 500 W: 70x25mm (PWM type)

Technical Specifications – Weights and Dimensions

WEIGHT AND DIMENSIONS

Chassis (W x D x H)	6.12 x 11.93 x 13.28 in (155 x 303 x 337 mm) (w/ bezel)
System Volume	15.1 L
System Weight*	10.4 lb / 4.7 kg
Packaged (H × W × D)	11.3 x 15.75 x 19.65 in 287 x 400 x 499 mm
Shipping Weight	17.64lb / 8 kg
Palletization Profile	6 units per layer 7layer max 42 per pallet Footprint -85.31x39.37x47.24 in (2167 x 1000 x1200 mm)



After-Market Options (availability may vary by region)

AFTERMARKET OPTIONS

Туре	Description	Part #
Memory	HP 4GB DDR4-3200 DIMM	13L78AA
	HP 8GB DDR4-3200 DIMM	13L76AA
	HP 16GB DDR4-3200 DIMM	13L74AA
	HP 32GB DDR4-3200 DIMM	13L72AA
Storage	HP PCIe NVME TLC 256GB SSD M.2 Drive	1CA51AA
	HP PCIe NVME TLC 512GB SSD M.2 Drive	X8U75AA
	HP PCIe Gen 4 NVME TLC M.2 512GB SSD	406L8AA
	HP PCIe Gen 4 NVME TLC M.2 1TB SSD	406L7AA
	HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive	QK554AA
	HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive	QK555AA
Graphics	NVIDIA T400 4GB GDDR6 3mDP	5Z7E0AA
Security	HP Business PC Security Lock V3 Kit	3XJ17AA
	HP Keyed Cable Lock 10mm kit	T1A62AA
Cables/Adapters	HP HDMI Standard Cable Kit	
	HP USB to Serial Port Adapter	J7B60AA
	HP PCIe x1 Parallel Port Card	N1M40AA
Networking	Intel Ethernet I225-T1 GbE NIC Card	406L9AA
Input	HP Wired Desktop 320K Keyboard	9SR37AA
	HP Wired Desktop 320M Mouse	9VA80AA
	HP 125 Wired Keyboard	266C9AA
	HP 125 Wired Mouse	265A9AA
	HP 128 Laser Wired Mouse	265D9AA
	HP Wired Desktop 320MK Mouse and Keyboard Combo	9SR36AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 225 Antimicrobial Wired Mouse and Keyboard Combo	286K3AA
Others	HP S101 Speaker bar	5UU40AA

Change Log

© Copyright 2023 HP Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein. Microsoft and Windows are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel, Celeron[®], Core, Pentium are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth is a trademark of its proprietor, used by HP Inc. under license. NVIDIA, GeForce, Kepler and NVS are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. AMD and Radeon are trademarks of Advanced Micro Devices, Inc. ENERGY STAR is a registered trademark owned by the U.S. Environmental Protection Agency.

Date of change:	Version History:	Change	Description of change:
June 13, 2023	From v1 to v2	Removal	Disclaimer from call outs front image, page 1
June 14, 2023	From V2 to V3	Removal	Call outs section, page 4
	From V3 to V4		
	From V4 to V5		
	From V5 to V6		
	From V6 to V7		
	From V7 to V8		
	From V8 to V9		
	From V9 to V10		
	From v10 to v11		
	From v11 to v12		
	From v12 to v13		
	From v13 to v14		